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SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

AZ9143-08F

Product specification

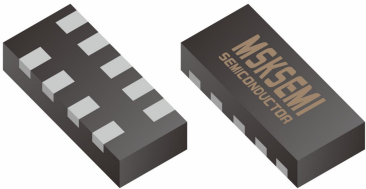
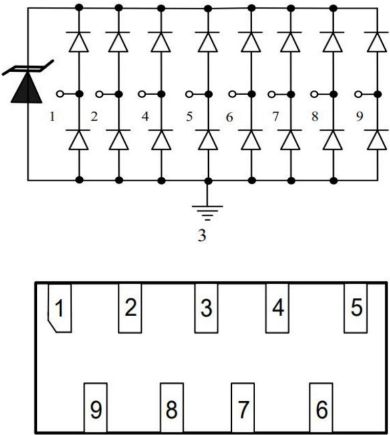
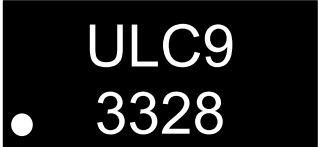
Features

- 150 Watts peak pulse power (tp = 8/20μs)
- Transient protection for high speed data lines to
IEC 61000-4-2 (ESD) ±15kV (air), ±8kV (contact)
IEC 61000-4-4 (EFT) 40A (5/50ns)
- Working voltages : 3.3V
- Protects eight I/O lines
- Low operating and clamping voltages
- Solid-state silicon avalanche technology

Application

- Notebooks, Desktops, Servers and Video Graphics Cards
- USB Power & Data Line Protection
- Monitors and Flat Panel Displays
- I²C Bus Protection
- Portable Instrumentation
- Set Top Box

Reference News

PACKAGE OUTLINE	Pin Configuration	Marking										
	 <table border="1" data-bbox="608 1395 963 1547"> <tr> <td>1</td> <td>2</td> <td>3</td> <td>4</td> <td>5</td> </tr> <tr> <td>9</td> <td>8</td> <td>7</td> <td>6</td> <td></td> </tr> </table>	1	2	3	4	5	9	8	7	6		
1	2	3	4	5								
9	8	7	6									
<p>DFN3810-9L</p>												

Maximum Rating @ Ta=25°C unless otherwise specified

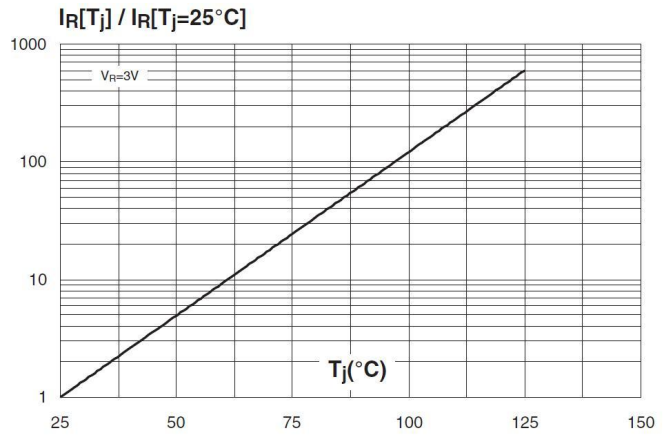
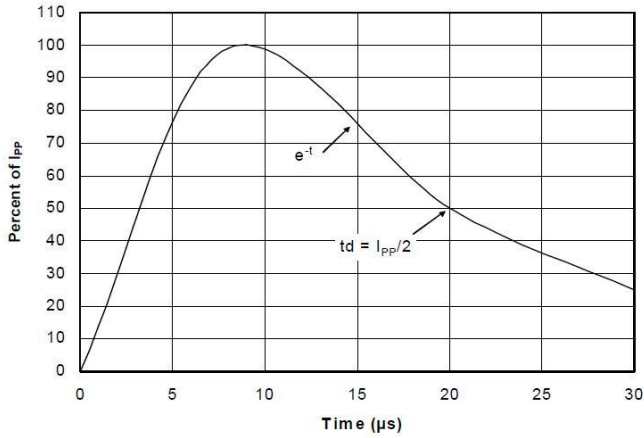
Symbol	Parameter	Ratings	Units
P _{PK}	Peak Pulse Power (tp = 8/20μs)	150	Watts
T _L	Lead Soldering Temperature	260(10sec.)	°C
T _J	Operating Temperature	-55 to + 125	°C
T _{STG}	Storage Temperature	-55 to + 150	°C

Electrical Characteristics@ Ta=25°C unless otherwise

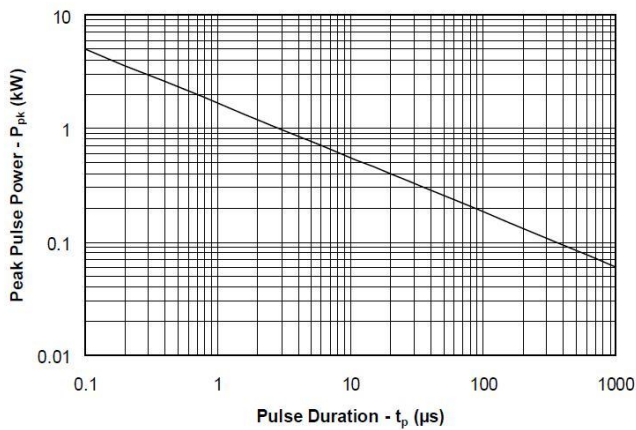
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V _{RWM}	Reverse Working Voltage	Any I/O to Ground			3.3	V
V _{BR}	Reverse Breakdown Voltage	I _T = 1mA, Any I/O to Ground	4.5			V
I _R	Reverse Leakage Current	V _{RWM} = 5V, Any I/O to Ground			1	μA
V _C	Clamping Voltage	I _{PP} = 1A, tp =8/20μs, any I/O pin to Ground			9.8	V
		I _{PP} = 3A, tp =8/20μs, any I/O pin to Ground			15	V
C _J	Junction Capacitance	V _R = 0V, f =1MHz, between I/O pins		0.3	0.5	pF
		V _R = 0V, f =1MHz, any I/O pin to Ground		0.5	0.8	pF

Typical Characteristics@ Ta=25°C unless otherwise specified

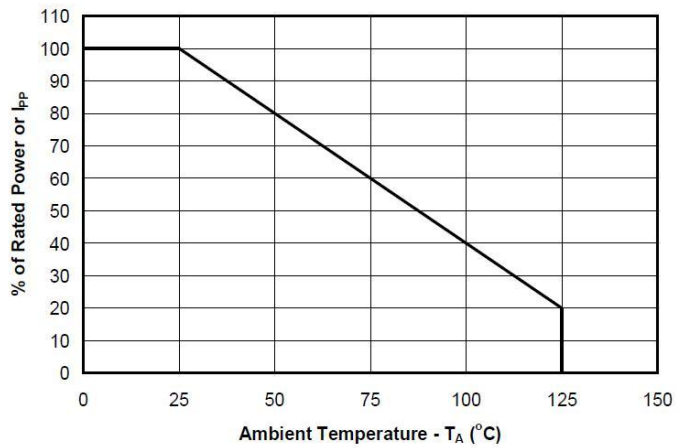
Pulse Waveform



Non-Repetitive Peak Pulse Power vs. Pulse Time

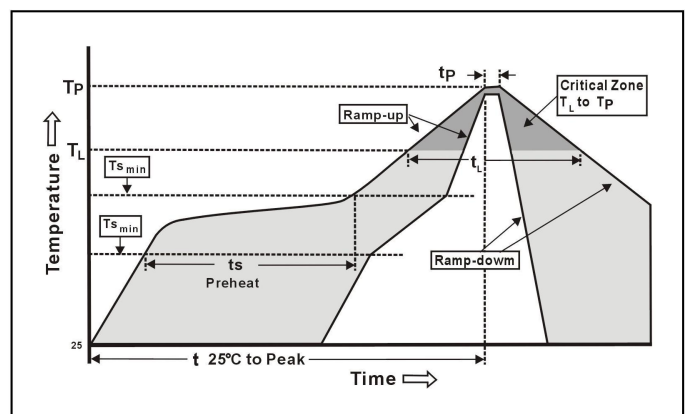


Power Derating Curve



Soldering Parameters

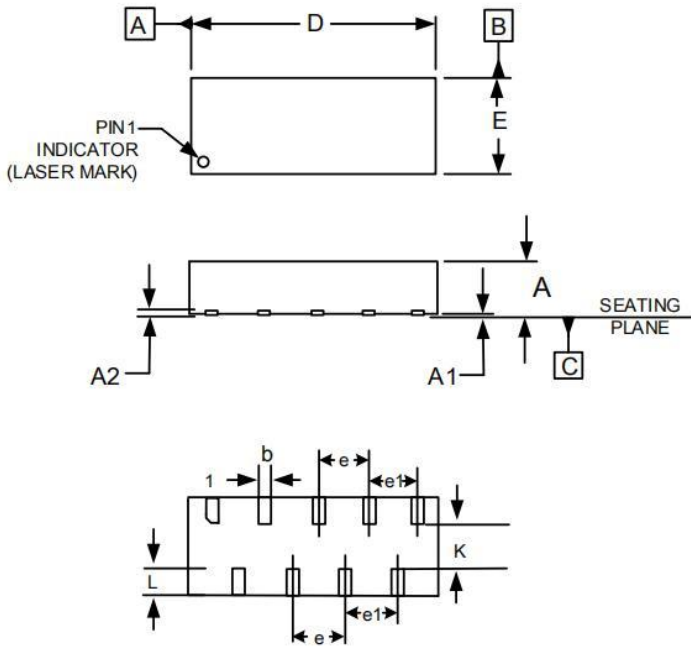
Reflow Condition		Fb – Free assembly
Pre Heat	- Temperature Min ($T_{s(Min)}$)	150°C
	- Temperature Max ($T_{s(Max)}$)	200°C
	- Time (Min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second Max
$T_{s(Max)}$ to T_L - Ramp-up Rate		3°C/second Max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_l)	60 – 150 seconds
Peak Temperature (T_p)		250 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second Max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



Package Outline

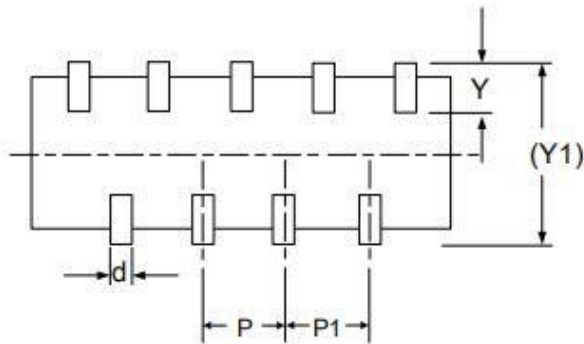
Plastic surface mounted package

DFN3810



DIM	MILLIMETERS		
	MIN	NOM	MAX
D	3.70	3.80	3.90
E	0.90	1.00	1.10
A	0.45	0.50	0.55
A1	0.00	0.02	0.05
A2	0.10	0.15	0.20
b	0.15	0.20	0.25
e	0.80BSC		
e1	0.90BSC		
L	0.20	0.30	0.40

Soldering Footprint



DIM	DIMENSIONS	
	INCHES	MILLIMETERS
P	0.031	0.80
P1	0.035	0.90
d	0.012	0.30
Y	0.024	0.60
Y1	0.061	1.55

Package And Marking Information

P/N	PKG	QTY
AZ9143-08F	DFN3810	3000

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